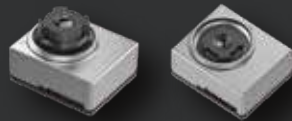


TIMO Series Miniature Thermal Modules

Boost Infrared Application of
Consumer Electronics Market

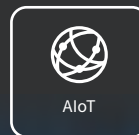
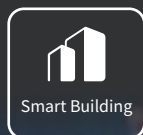


TIMO-120



TIMO-256

The wafer-level package infrared module integrates wafer-level optical lens, wafer-level package detector, and basic imaging processing circuit to achieve accurate temperature data and sharp images for each pixel in the full frame, enabling easy integration into mobile terminals or smart devices, especially innovative products with strict requirements on cost, size and weight.



“Low cost, fast integration”

- Minimum WLP infrared module, dimension at 8.5X8.5X9.16mm.
- DVP Interface, compatible with various embedded platforms.
- Visible camera module equivalent, directly integration.
- Complete SDK development kit.



“Extend longer operating time”

- Low-power design, lowest to 9mW.



Model	TIMO-120	TIMO-256
IR Detector Performance		
Resolution	120×90	256×192
Pixel Pitch	17μm	12μm
Spectral Range	8~14μm	
NETD	≤60mK	≤45mK
Lens Type	WLO	
Focus	Fixed zoom	
HFOV	90°/50°	53°±1°
Depth of Field	10cm to infinity	
Frame Rate	1~30Hz (Customizable)	
Temperature Measurement		
Temperature Range	-20°C ~ +120°C (Customizable)	
Temperature Accuracy	Customizable (Meet the requirements of body or industrial thermography)	
Interface / Control		
AVDD	3.6V±0.05V	
VSK/VDET	4.7V±0.05V	5.0±0.05V
DVDD	1.8V±0.05V	
Interface	Digital Interface	
Power Consumption	45mW (Typical Mode) ;9mW (Low Power Mode)	70mW
Physical Characteristic		
Dimension(mm)	12X10X5.48 (HFOV=90°) 8.5X8.5X9.16 (HFOV=50°) (The specifications shall prevail)	15X13X6.83(The specifications shall prevail)
Operation Temperature	-20°C ~ +60°C	
Storage Temperature	-40°C ~ +85°C	

Specifications are subject to change without notice.

Wuhan Global Sensor Technology Co., Ltd

☎ 400-027-0198

✉ marketing@gst-ir.com

🌐 www.gst-ir.com

📍 No.6, Huanglongshan South Rd, Wuhan, Hubei, China

